PRODUCT/PROCESS CHANGE NOTIFICATION

PCN MMS-MIC/09/4961
Notification Date 09/25/2009

DIP16 assembly transfer from ST Shenzhen (China) to ST Longhang (China)

Table 1. Change Implementation Schedule

Forecasted implementation date for change	18-Sep-2009
Forecasted availabillity date of samples for customer	18-Sep-2009
Forecasted date for **STMicroelectronics** change Qualification Plan results availability	18-Sep-2009
Estimated date of changed product first shipment	18-Dec-2009

Table 2. Change Identification

Product Identification (Product Family/Commercial Product)	All DIP16 part numbers
Type of change	Package assembly location change
Reason for change	Closure of ST Shenzhen assembly line
Description of the change	MCD is pleased to announce the qualification of ST Longhang (China) assembly site for all MCUs in DIP16. Successful completion of the qualification plan as shown page 5 will allow for production of the affected devices. There are no changes to the devices design or part number as a result of this change.
Product Line(s) and/or Part Number(s)	See attached
Description of the Qualification Plan	See attached
Change Product Identification	Assembly plant code on the marking from "GK" to "G4"
Manufacturing Location(s)	

Table 3. List of Attachments

Customer Part numbers list	
Qualification Plan results	

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Customer Acknowledgement of Receipt **PCN MMS-MIC/09/4961**

Please sign and return to STMicroelectronics Sales Office **Notification Date 09/25/2009**

☐ Qualification Plan Denied	Name:
☐ Qualification Plan Approved	Title:
	Company:
☐ Change Denied	Date:
☐ Change Approved	Signature:

Remark

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DOCUMENT APPROVAL

Name	Function
Colonna, Daniel	Division Marketing Manager
Nicholas, Jimmy Edward	Division Product Manager
Narche, Pascal	Division Q.A. Manager

MCD Pkg09 02 QC
QUALIFICATION CERTIFICATE

Date : 09/ 14/ 2009

Assembly Plant : ST Longhang (LGG) China

Package : PDIP16

Product : All

Process : Leadfree, NiPdAu lead termination

Materials :

D/A Material	QMI168 GLUE
M/C Material	RESIN KCC KTMC1000 1030SL
Wire	GOLD WIRE: 1 MIL DIAMETER 25µ

Conclusion :

PDIP 16 package, assembled in ST LGG, NiPdAu leadfree plating is QUALIFIED.

CERTIFIED by:

Gisèle SEUBE
Microcontroller Division QA Dept
Rousset Sept 14th

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